

Date : 2006. 11. 20.

Ref. No :

To : Application Examiner / Reviewing Engineer
FCC Laboratory
7435 Oakland Mills Road
Columbia, MD 21046

CC :

Subject : Class II Permissive Change on FCC ID: P3HCDP-NW10

Applicant: KI RYUNG ELECTRONICS CO., LTD., FCC ID: S3HCDP-NW10

Our above client, KI RYUNG ELECTRONICS CO., LTD., is submitting a Class II Permissive Change as per 47 CFR Part 2.1043 for FCC ID: S3HCDP-NW10.

The modification and/or changed items are as follows.

1. Delete Speaker connector's Ferrite Cores.
2. Delete Servo Board's Copper plate.
3. Attach 2 Core(CU1330B) to DC Power line. For reduce connector's radiation.
4. Attach a Core(CU0530G) to 4P connector. For reduce connector's radiation.
5. Attach a Core(CU0903B) to 15P connector. For reduce connector's radiation.
6. Attach a Gasket(71TS FK-5-4-10-15) to Audio Port. For GND Stability.
7. Attach 2 Gaskets(71TS FK-5-4-25-15) to Amp PCB's Chassis. For GND Stability.
8. Attach a Core(CU0530G) to 15P Cable closely to Amp. For reduce connector's radiation.
9. Solder a Finger(EXF-0022) to Amp PCB both side. For GND Stability.
10. Add Cap chips C202, C203(1nF) to each OSC in Main PCB. For reduce EMI element.
11. Add Res chip R266(33R) to SPDIF line in Main PCB. For reduce EMI element.
12. Change Res Chip R73, R83, R93, R95(33ohm) to Bead6, Bead8, Bead9, Bead10(SBK160808T-221Y) in Main PCB. For reduce connector's radiation.
13. Add FB2, FB3, FB4, FB5(SBK160808T-121Y) in Amp PCB. For reduce 12p connector's radiation.
14. Change Res Chip R30, R41, R43, R44(220ohm) to 33ohm. And add Cap chip C41, C42, C43, C44(47pf) in Amp PCB. For reduce EMI element.
15. Delete Surge diodes D1, D4, D5, D7(P6SMBJ33CA) in Amp PCB. For reduce EMI element.

We have included radiated/conducted emission test result and photos for the product.

If you have any questions or concerns, feel free to contact me.

Best regards,



Y. K. Kwon / Director

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